

Micro Commercial Components Corp.

PB Free finish plan

Title: Pb (lead) Free Finish(Plating Conversion)

First Anticipated Available Date : Jan.1st , 2004

Last Anticipated Available Date : Jun. 1st , 2004

Description and Purpose: Pb(Lead) Free Finish Conversion

This is a General Announcement that Micro Commercial Components Corp(MCC). is converting the External Lead Finish(Plating) to a Pb (lead) Free Finish(Plating process). MCC recognizes the increasing demand for environmentally friendly products. MCC will convert the existing Sn-Pb plating finish to a Pb Free solution on a package by package basis. This conversion will take place from Jan. 2004 to Jan.2005, with approximately two conversion phases. This general announcement will be followed by Process Change Notifications (PCNs) prior to each package being converted. The PCNs will include the complete list of affected devices which we will produce.

Plating Compositions – The Pb containing lead finish composition and the new Pb Free lead finish compositions will be noted on the PCN for each package type.

Moisture Sensitivity Level (MSL) – Axial devices and Surface Mount Packages are qualified to 260 degrees C, which is a higher temperature profile than the JEDEC standard J-STD-020B. The majority of the MSL ratings will remain unchanged from the current MSL 1 classification. The MSL rating will be noted on the PCN for each package type. If there is a change in the MSL rating of a package, appropriate packing precautions will be taken before any product is shipped by Micro Commercial Components Corp.

Compatibility –Micro Commercial Components Corp. has tested the forward and backward compatibility of axial Devices and Surface Mount Devices (SMD). Forward compatibility refers to the ability of current Pb containing lead finishes to be used with Pb Free solder preform. Backward compatibility refers to the ability of the new Pb Free lead finishes to be used with Pb containing solder preforms. All of Micro Commercial Components Corp 's Pb containing lead finishes are forward compatible. A change in the MSL rating @ 260 degrees C must be taken into account for handling product outside the packing.

Available Date – The noted Anticipated Conversion Date refers to the date the Pb Free Plating Production Process will be available. Pb free plating product will have –TP or –BP at the end of part number (-TP for pb free tape&reel and –BP for pb free bulk).

Phase 1		
Anticipated Available Date: Jan. 1st 2004		
Samples and Reliability, Available now		
Package	Type	Plating Material
DO-41	STD FR HER SKY GPP Rectifier Zener Tvs	Pure tin
R-1	STD FR HER SKY GPP Rectifier Zener Tvs	Pure tin
A-405	STD FR HER SKY GPP Rectifier Zener Tvs	Pure tin
DO-15	STD FR HER SKY GPP Rectifier Zener Tvs	Pure tin
DO-201A	STD FR HER SKY GPP Rectifier Zener Tvs	Pure tin
R-6	STD FR HER SKY GPP Rectifier Zener Tvs	Pure tin
T-18	STD FR HER SKY GPP Rectifier Zener Tvs	Pure tin
DO-41,DO-35(glass)	SKY Rectifier , Zener	Pure tin
Melf,minimelf,micromelf(glass)	SKY Rectifier , Zener	Pure tin

Phase 2		
Anticipated Available Date: Jun. 1st 2004		
Samples and Reliability available		
Package	Type	Plating Material
SMAL	STD FR HER SKY GPP Rectifier Zener Tvs	Pure tin
SMAH	STD FR HER SKY GPP Rectifier Zener Tvs	Pure tin
SMAE	STD FR HER SKY GPP Rectifier Zener Tvs	Pure tin
SMAG	STD FR HER SKY GPP Rectifier Zener Tvs	Pure tin
SMB	STD FR HER SKY GPP Rectifier Zener Tvs	Pure tin
SMC	STD FR HER SKY GPP Rectifier Zener Tvs	Pure tin
TO-220	SKY GPP Rectifier	Pure tin
TO-92,TO-18	Transistor	Pure tin
SOT-23,323	SKY , Transistor	Pure tin
SOD123,323	SKY, Rectifier	Pure tin
MBS, RB,WOM	STD Rectifier	Pure tin